

PATENT
Atty. Dkt. No. APPM/005538/PPC/CMP/CKIM

IN THE CLAIMS:

Please cancel claims 27-55 and 59-76 without prejudice, and amend the claims as follows:

1-55. (Canceled)

56. (Currently Amended) The A method of claim 55 for planarizing a substrate having a conductive material layer and a barrier layer deposited thereon, comprising:
applying a conductive-material-layer-selective composition to a polishing pad,
wherein the conductive-material-layer-selective composition comprises:

at least one chelating agent;

at least one oxidizer;

at least one corrosion inhibitor; and

water;

polishing the substrate in presence of the conductive-material-layer-selective composition;

applying a barrier-layer-selective composition to the polishing pad, the barrier-layer-selective composition comprising:

at least one reducing agent;

ions from at least one transitional metal; and

water, and

polishing the substrate in presence of the barrier-layer-selective composition.

57. (Original) The method of claim 56, wherein the conductive-material-layer-selective composition further comprises at least one pH adjusting agent.

58. (Original) The method of claim 56, wherein the conductive-material-layer-selective composition further comprises abrasive particles.

59-76. (Canceled)